

IN THE CLAIMS

Please amend the claims as follows:

*Sub C1* 4. (Amended) The process chamber airflow system as claimed in claim 3, wherein the air diffuser eliminates initial airflow turbulence entering the plenum from an air filter.

*Sub C1* 6. (Amended) The process chamber airflow system as claimed in claim 5, wherein individual holes, included in the plurality of holes, have varying cross-sectional areas.

*Sub C1* 7. (Amended) The process chamber airflow system of claim 1, wherein the air diffuser is formed of static charge dissipating material.

*Sub C1* 9. (Amended) The process chamber airflow system of claim 1, wherein the air diffuser is disposed on one side of a generally cubic chamber of a semiconductor production device.

*Sub C1* 11. (Amended) The process chamber airflow system of claim 1, wherein the air diffuser diffuses air such that contaminant particles are removed from the chamber by the chamber airflow.

*Sub C1* 17. (Amended) The process chamber airflow system as claimed in claim 13, wherein [an] individual holes, included in the plurality of holes, have varying cross-sectional areas.

*Sub C1* 18. (Amended) The air diffuser of claim 13, wherein the plate is formed of static charge dissipating material.

*Sub C1* 19. (Amended) The air diffuser of claim 13, wherein the air diffuser diffuses air with a substantially laminar flow.

*sub c'* 21. (Amended) A method of providing substantially laminar airflow in a process chamber, comprising:

generating an initial flow of air with an initial cross-sectional area;

disposing an air diffuser with a plurality of uniformly spaced hole in the airflow, wherein a total cross-sectional area of the plurality of holes is less then the initial cross-sectional area; creating a back-pressure of air due to the reduction in the cross-sectional area through the plurality of holes;

dispersing a portion of the initial airflow uniformly across the air diffuser; and

providing uniform airflow through the plurality of holes included in the air diffuser, to the process chamber.

*sub c'* 24. (Amended) The process chamber airflow system of claim 22, wherein the air diffuser is formed of static charge dissipating material.

*sub c'* 25. (Amended) The process chamber airflow system of claim 22, wherein the air diffuser diffuses air, such that contaminate particles are removed from the chamber by the chamber airflow.